BOMcheck.net

# Full Material Declaration for attached parts list

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Diotec Semiconductor AG
**DUNS number:** 330866844
-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany
**Declarations authorised by:**
Udo Steinebrunner, Product Manager, -

## **Declaration effective from:** 1 October 2020 [Approved on 24 January 2022, 09:23 GMT]

**Materials and substances**

| Use/Location | Material Group | % w/w of material in the part | Substances in the material | CAS Number | % w/w of substance in the material |
|---|---|---|---|---|---|
| Chip (die) | Other inorganic materials | 7.52% | Silicon | 7440-21-3 | 100% |
| Die attach | Silver plating | 0.55% | 1,4-BIS(2,3-EPOXYPROPOXY)BUTANE | 2425-79-8 | 6% |
| | | | Epoxy resin 89 | 26335-32-0 | 12% |
| | | | Silver | 7440-22-4 | 82% |
| Encapsulation | EP (Epoxy resin) | 45.83% | Carbon black | 1333-86-4 | 0.85% |
| | | | Phenol | 108-95-2 | 1.15% |
| | | | Epoxy resin 89 | 26335-32-0 | 2% |
| | | | Silica | 7631-86-9 | 9% |
| | | | Quartz sand | 60676-86-0 | 87% |
| Inner preparation | Copper (e.g. copper amounts in cable harnesses) | 7.42% | Copper (metallic) | 7440-50-8 | 100% |
| Leadfinish | Tin plating | 7.8% | Tin | 7440-31-5 | 100% |
| Leadframe | Copper (e.g. copper amounts in cable harnesses) | 30.88% | Zinc | 7440-66-6 | 0.1% |
| | | | Silver | 7440-22-4 | 0.6% |
| | | | Iron | 7439-89-6 | 2.5% |
| | | | Copper | 7440-50-8 | 96.8% |

### Attached parts list

| Part number | Part name | Part Mass | Part Mass UoM |
|---|---|---|---|
| QFN3x3 | Diode/Transistor Power | 0.1 | g |